



**MMBT3906**

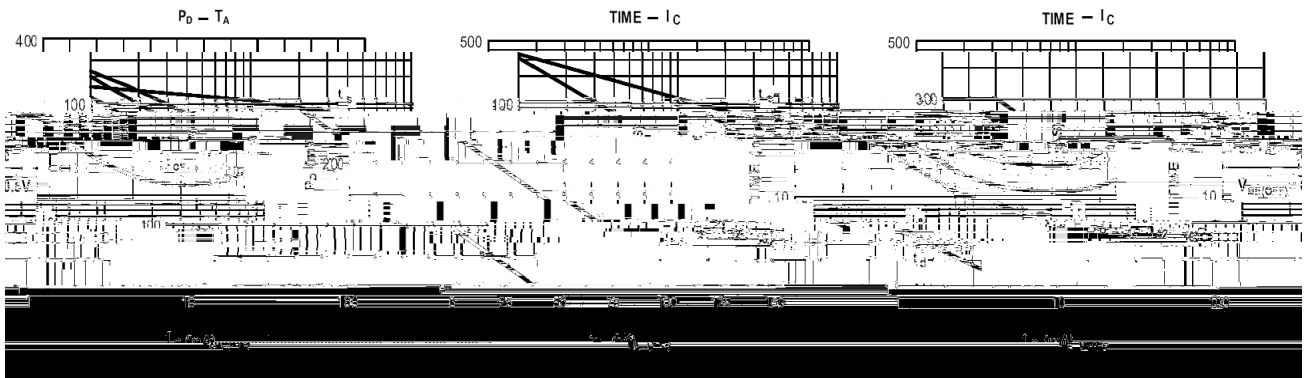
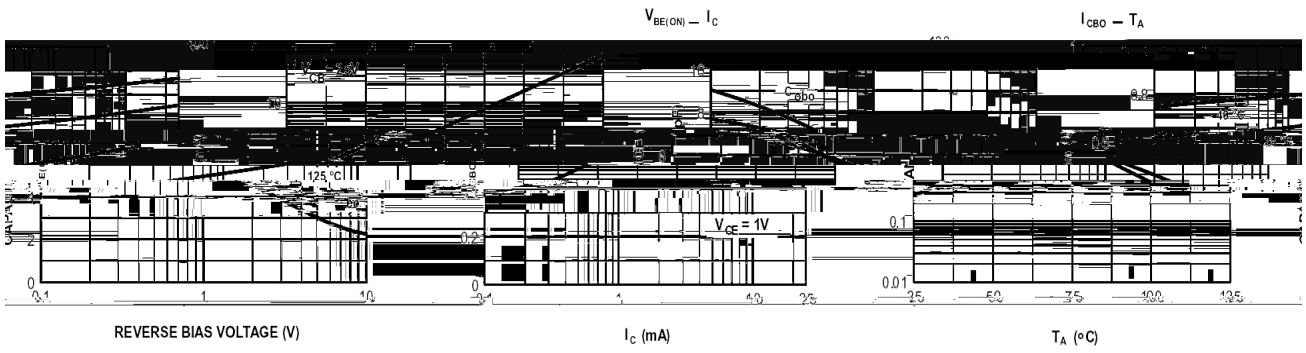
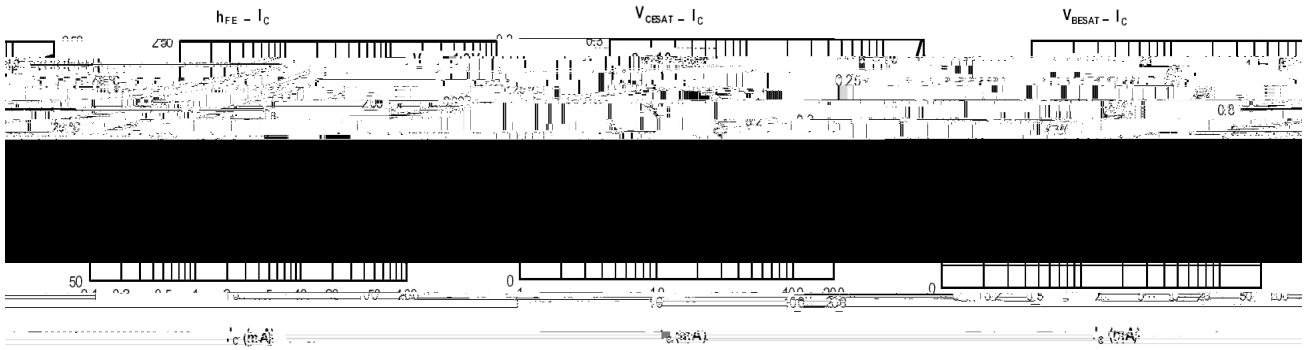


Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	-40	V
Collector to Emitter Voltage	$V_{CEO}$	-40	V
Emitter to Base Voltage	$V_{EBO}$	-5.0	V
Collector Current	$I_C$	-200	mA
Collector Power Dissipation	$P_C$	300	mW
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

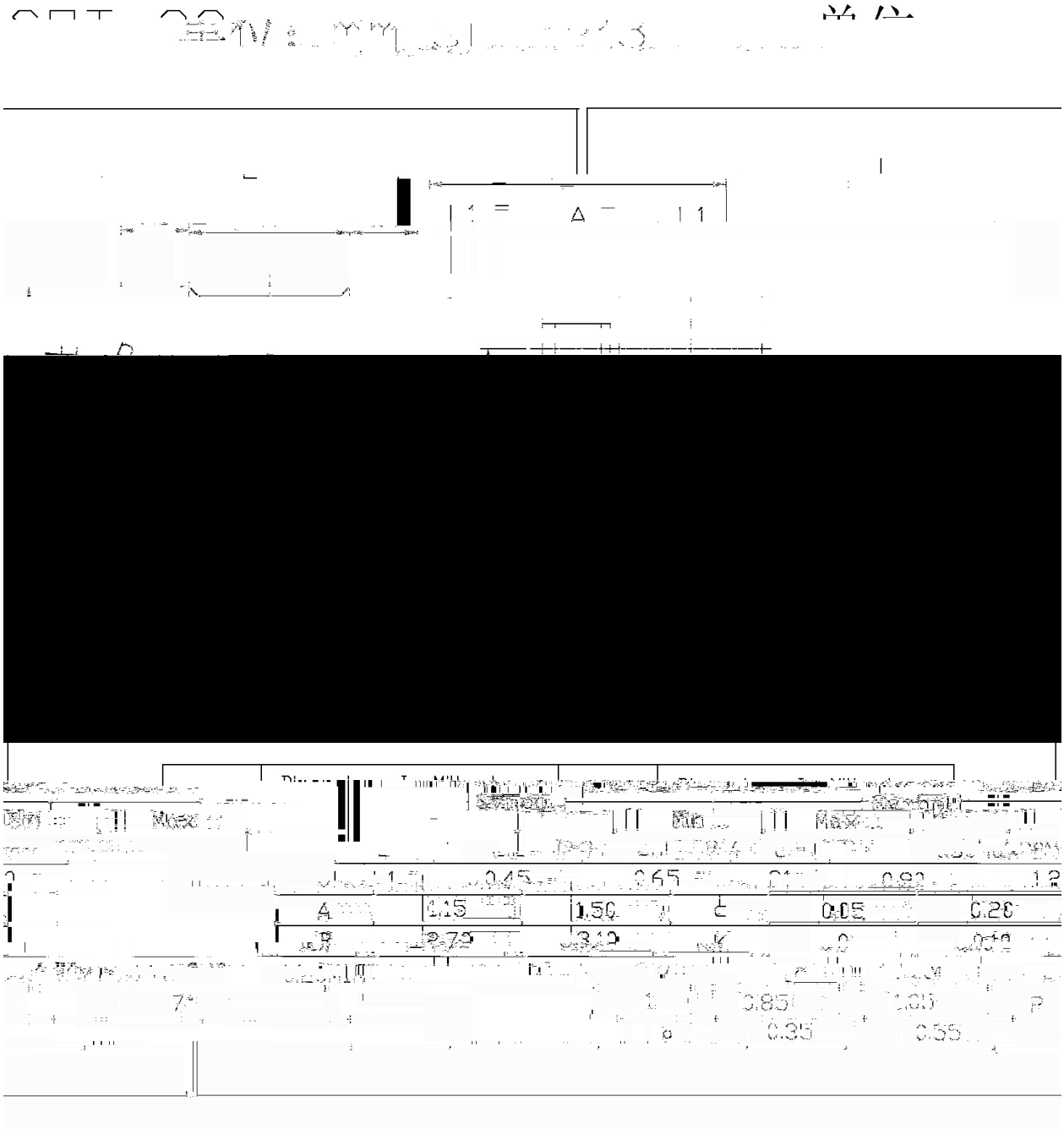
Parameter                      Symbol                      Test Conditions                      Min      T



**/ Electrical Characteristic Curve**

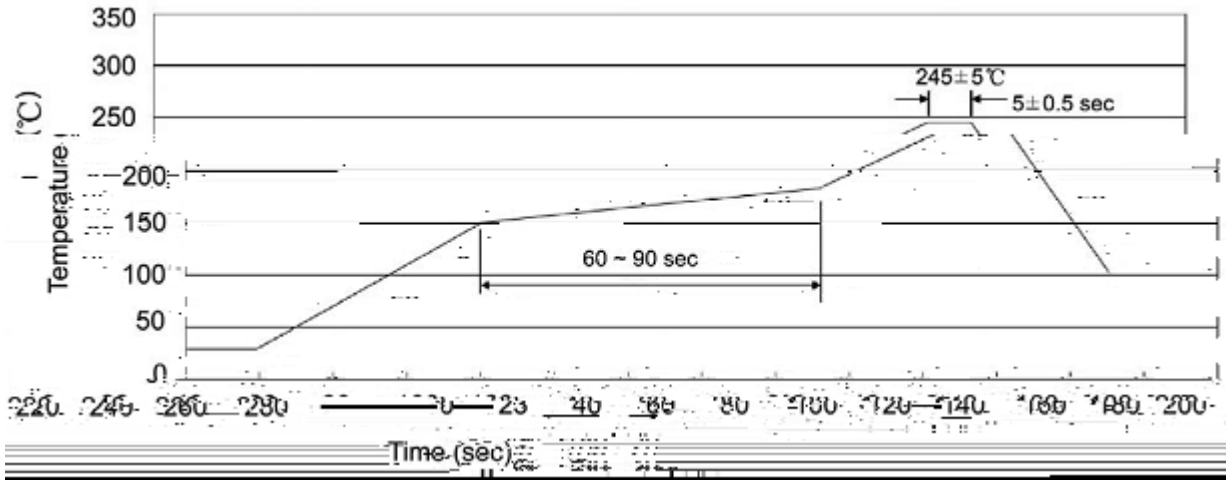


**/ Package Dimensions**





( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |    |           |   |
|---|-------|-----|----|-----------|---|
| 1 | 25    | 150 | 60 | 90sec;    | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     |    | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       |     | 2  | 10 /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5°C                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type                      Units                      Dimension                      (unitfi mm<sup>3</sup>)